Resistors

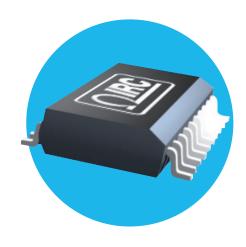
OBSOLETE



TaNCap® AC Line **Termination Network**

AC Terminator Series

- Improves signal quality
- Reduces power dissipation
- Highly integrated replaces up to 36 discretes
- RoHS compliant and Sn/Pb terminations available
- Proven TaNCap® thin film technology in QSOP, SOIC, and TSSOP packages



All Pb-free parts comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

Today's high speed digital circuits demand top performance while maintaining low power dissipation. IRC's TaNCap® AC termination networks are designed to meet the needs of the digital circuit designer by blocking DC current flow into the terminating resistor during the steady-state portion of the digital signal while passing current into the tantalum nitride terminating resistor during the presence of signal edges and transients.

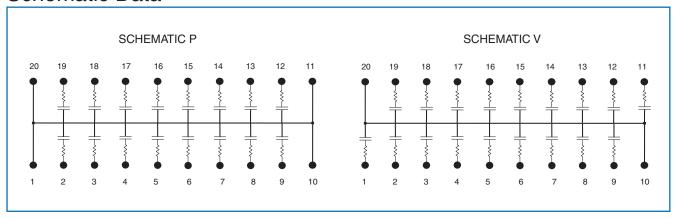
The SOIC, QSOP, and TSSOP packages offer a high level of integration in today's most popular surface mount configurations. One AC Termination network replaces up to 36 discrete components.

The TaNCap® series of resistor-capacitor networks are manufactured using IRC's military and space proven tantalum nitride thin film technology. For high reliability combined with superior performance, use IRC TaNCap® AC termination networks for your high speed, digital circuit applications.

Electrical Data

	Range	Tolerance (%)	Breakdown Voltage (volts)	TCR (ppm/°C)	Max. Power Dissipation (watts)	Operating Temp. Range (°C)
Resistors	10 Ω to 100 Ω	±10	N/A	±100	0.1 per resistor	-55 to +125
Capacitors	10pF to 200pF	±20	25	N/A	N/A	-55 to +125

Schematic Data



BI Technologies IRC Welwyn

TaNCap® AC Line Termination Network

AC Terminator Series

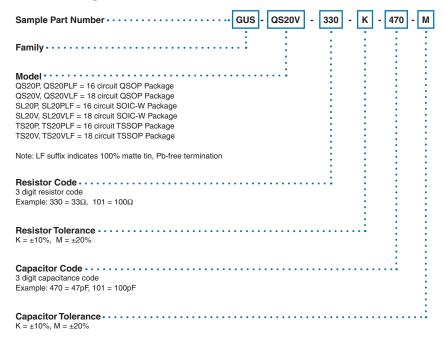
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Physical Data

Model	Body Type	# Pins	Reference IRC Datasheet
QS20x	QSOP	20	Surface Mount QSOP Termination Networks
SL20x	SOIC-W	20	Surface Mount SOIC Termination Networks
TS20x	TSSOP	20	Surface Mount TSSOP Termination Networks

Ordering Data



Packaging Available

Tubes, Tape & Reel

For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below